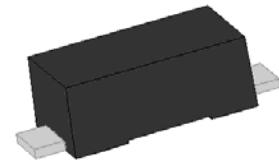




DESCRIPTION:

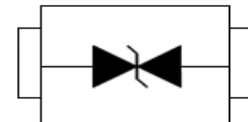
The JEBxxD1FT series are designed to protect sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD) and other voltage induced transient events.



SOD-123FL

FEATURES

- ✧ 3600W to 6600W peak pulse power dissipation at 1.2/50 μ s-8/20 μ s@2 Ω waveform.
- ✧ For small surface mounted applications.
- ✧ Response time is typically <1ns.
- ✧ Low clamping voltage.
- ✧ Low leakage current.
- ✧ RoHS compliant.
- ✧ Meets MSL level 1, per J-STD-020, LF maximum peak of 260 $^{\circ}$ C.
- ✧ Terminal: solder plated, solderable per J-STD-002.



Pin configuration

MAIN APPLICATIONS

- ✧ Cell phone handsets and accessories
- ✧ Personal digital assistants (PDA's)
- ✧ Notebooks, desktops, and servers
- ✧ Portable instrumentation

PROTECTION SOLUTION TO MEET

- ✧ IEC61000-4-2 (ESD) \pm 30kV (air), \pm 30kV (contact)
- ✧ IEC61000-4-5 (Lightning) 200A (1.2/50 μ s-8/20 μ s@2 Ω)

MECHANICAL CHARACTERISTICS

- ✧ SOD-123FL package
- ✧ Molding compound flammability rating: UL 94V-0
- ✧ Typical weight: 0.0144g/pcs
- ✧ Lead finish: lead free

ABSOLUTE MAXIMUM RATINGS ($T_A=25^{\circ}\text{C}$, RH=45%-75%, unless otherwise noted)

Parameter	Symbol	Value	Unit
Peak pulse power dissipation at 1.2/50 μs -8/20 μs @2 Ω waveform	P _{PP}	3600 to 6600	W
Peak pulse current at 1.2/50 μs -8/20 μs @2 Ω waveform	I _{PP}	200	A
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V _{ESD}	+/- 30 +/- 30	kV
Lead soldering temperature	T _L	260 (10 sec.)	$^{\circ}\text{C}$
Operating junction temperature range	T _J	-55 to +150	$^{\circ}\text{C}$
Storage temperature range	T _{STG}	-55 to +150	$^{\circ}\text{C}$

ELECTRICAL CHARACTERISTICS ($T_A=25^{\circ}\text{C}$)

Part Number	Marking	V _R	I _{R@V_R}	V _{BR@I_T}		I _T	P _{PP} ^①	V _H ^②	V _{C@I_{PP}}	I _{PP} ^②
				min(V)	max(V)					
Bi-Polar	Bi	V	max(μA)	min(V)	max(V)	mA	W	typ(V)	max(V)	A
JEB07D1FT	J07B	7	1.0	8.0	10.0	1	3600	NA	18.0	200
JEB09D1FT	J09B	9	1.0	9.5	11.5	1	4600	NA	23.0	200
JEB12D1FT	J12B	12	1.0	13.0	15.0	1	5600	NA	28.0	200
JEB15D1FT	J15B	15	1.0	16.5	19.5	1	6000	NA	30.0	200
☆JEB18D1FT	J18B	18	1.0	19.5	23.5	1	6600	18.0	33.0	200
☆JEB20D1FT	J20B	20	1.0	22.2	24.5	1	6600	19.0	33.0	200
☆JEB24D1FT	J24B	24	1.0	25.0	30.0	1	6400	22.0	32.0	200

①Peak pulse power dissipation (Surge waveform: 1.2/50 μs -8/20 μs @2 Ω)

②Peak pulse current (Surge waveform: 1.2/50 μs -8/20 μs @2 Ω)

V_R: Stand-off voltage -- Maximum voltage that can be applied

V_C: Clamping voltage -- Peak voltage measured across the suppressor at a specified I_{PP}

V_{BR}: Breakdown voltage

I_R: Reverse leakage current

☆: Products with negative resistance

RATINGS AND V-I CHARACTERISTICS CURVES ($T_A=25^{\circ}\text{C}$, unless otherwise noted)

FIG.1:V- I curve characteristics (Bi-directional)

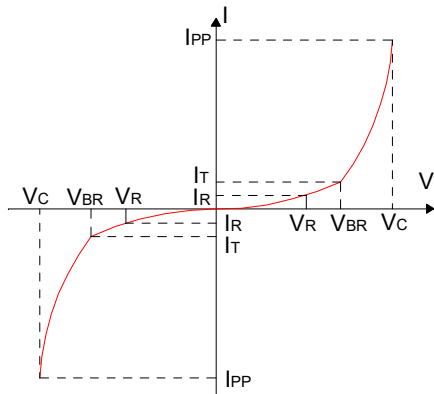


FIG.2:V- I curve characteristics (Bi-directional with negative resistance)

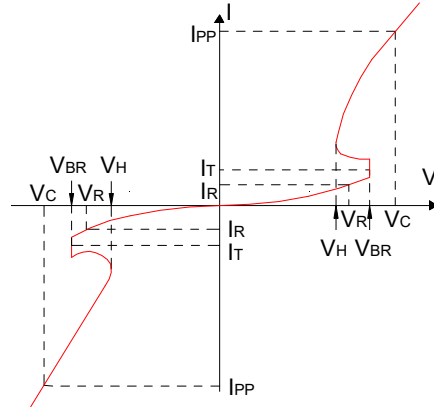


FIG.3: Pulse waveform (1.2/50μs)

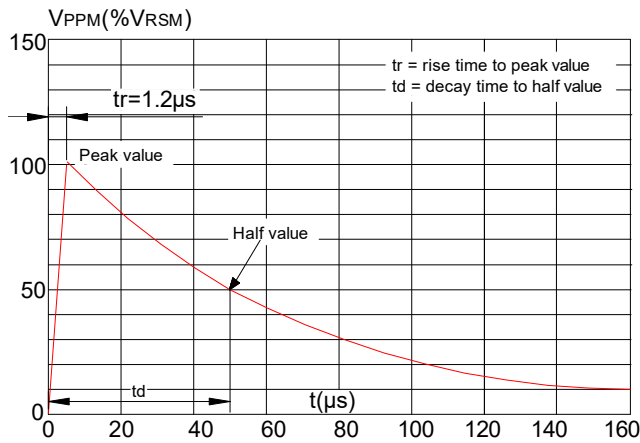


FIG.4: Pulse waveform

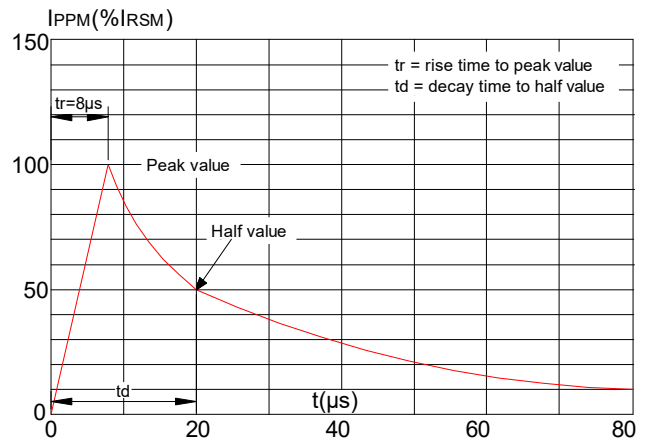


FIG.5: ESD clamping (30kV contact)

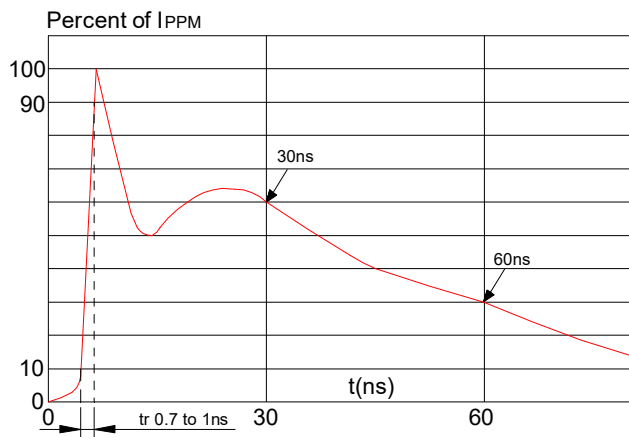
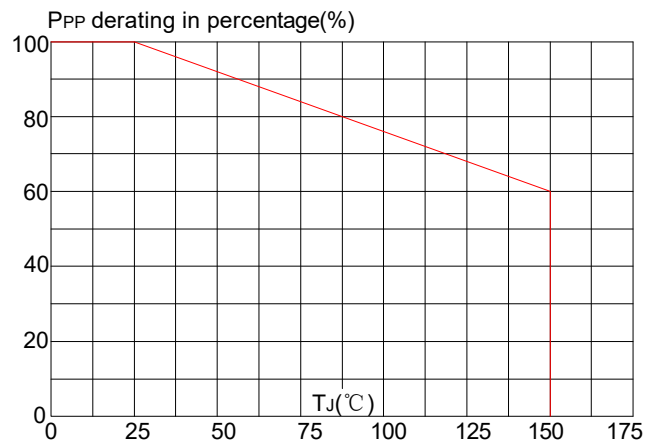
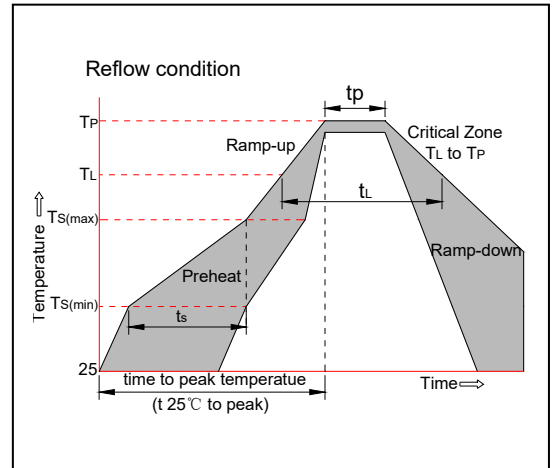


FIG.6: Pulse derating curve

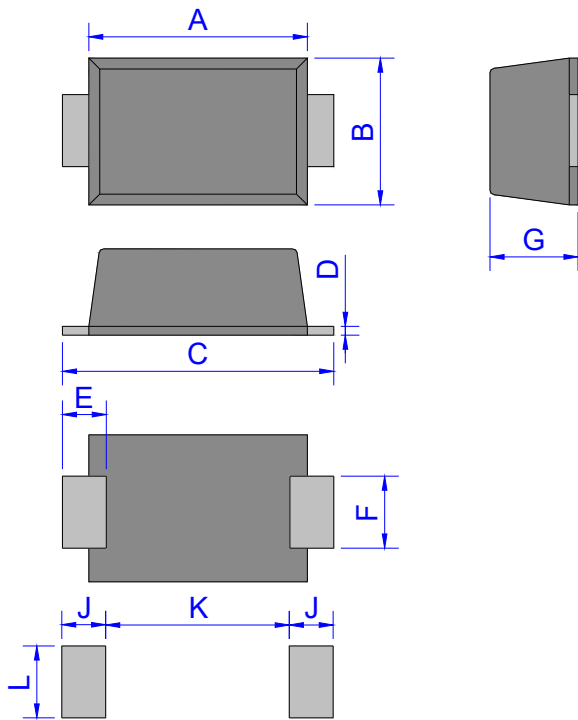


SOLDERING PARAMETERS

Reflow Condition		Pb-Free assembly (see figure at right)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150°C
	-Temperature Max($T_{s(max)}$)	+200°C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquidus Temp (T_L)to peak)		3°C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature(T_L)(Liquidus)	+217°C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_p)		20-40secs.
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp (T_p)		8 min. Max
Do not exceed		+260°C



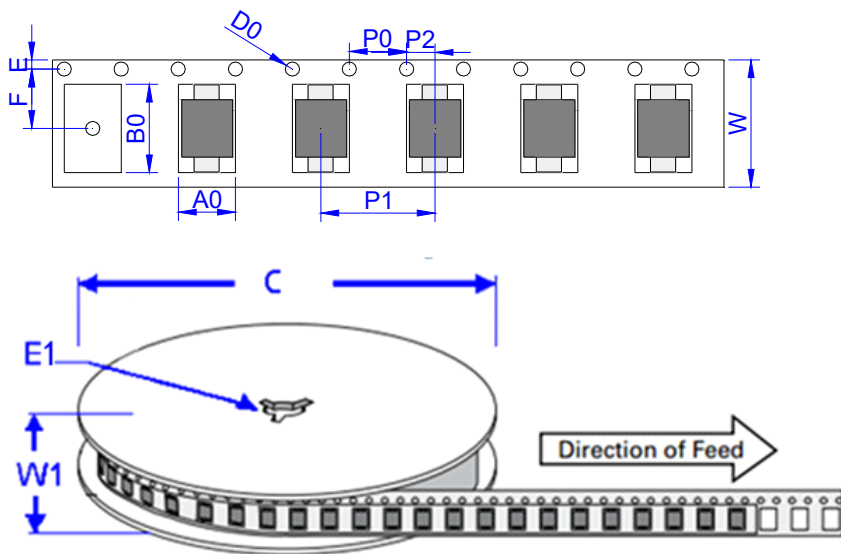
PACKAGE MECHANICAL DATA



SOD-123FL

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	2.60	3.00	0.102	0.118
B	1.60	2.00	0.063	0.079
C	3.45	3.95	0.136	0.156
D	0.10	0.25	0.004	0.01
E	0.3	0.9	0.012	0.035
F	0.80	1.20	0.031	0.047
G	0.70	1.00	0.028	0.039
J	1.30		0.051	
K		1.70		0.067
L	1.30		0.051	

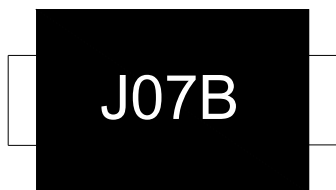
TAPE AND REEL SPECIFICATION-SOD-123FL



Ref.	Dimensions	
	Millimeters	Inches
A0	1.95 ± 0.3	0.077 ± 0.012
B0	3.95 ± 0.3	0.156 ± 0.012
C	178	7.0
D0	1.55 ± 0.1	0.061 ± 0.004
E	1.75 ± 0.2	0.069 ± 0.008
E1	13.3 ± 0.3	0.524 ± 0.012
F	3.50 ± 0.2	0.138 ± 0.008
P0	4.00 ± 0.2	0.157 ± 0.008
P1	4.00 ± 0.2	0.157 ± 0.008
P2	2.00 ± 0.2	0.079 ± 0.008
W	8.0 ± 0.2	0.315 ± 0.008
W1	11.5 ± 1.0	0.453 ± 0.039

PART No.	UNIT WEIGHT (g/PCS) typ.	REEL (PCS)	PER CARTON (PCS)	DESCRIPTION
JEBxxD1FT	0.0144	3000	150,000	7 inch reel pack

MARKING CODE



J07B : Device Marking Code

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